



The 17th IEEE ICICDT 2019
International Conference on IC Design & Technology
Suzhou, China, June 17th– 19th, 2019
<http://www.ICICDT.org>



The International Conference on IC Design and Technology (ICICDT) is the global forum for interaction and collaboration of IC design and technology for "Promoting scientific and technological progress, accelerating product time-to-market". Close collaboration of the multi-discipline technical fields design/device/process accelerates the implementation of new designs and new technologies into manufacturing. This conference has been organized by worldwide committee members from industry and academia since 2003. The meeting venue has been in Europe, North America and Asia for the past 16 years, and in 2019 the 17th IEEE ICICDT will be firstly held in mainland China. We extend our invitation to you to submit papers, present and discuss your works at the 17th IEEE ICICDT 2019 conference in this exciting field. The conference proceedings will be collected in IEEE publication database - IEEE X^plore and indexed by EI Compendex.

2019 ICICDT Venue:

The venue of 2019 International Conference on IC Design and Technology (ICICDT) will be at [Guanyuan Liusu Hotel Suzhou](#) (Originally known as "Suzhou Jinling Guanyuan International Hotel"), situated by Suzhou's Dushu Lake (14 km from the walled historic town) and about 70 km from Shanghai Hongqiao international airport and about 120 km from Shanghai Pudong international airport.

Contributed papers are solicited but not limited in the following subject areas:

- Advanced materials and processing technologies, power semiconductor technologies and circuits
- Advanced transistor and interconnect structures
- Advanced packaging, vertical (2.5D/3D) integration
- Variation and fault-tolerant designs, reliability issues and mitigation approaches, EDA and design optimizations across system, circuit, and/or device levels for high performance, energy efficiency, yield, and/or reliability
- RF, analog, mixed signal, and I/O circuits for future technology generations
- Simulation and modeling of advanced processes, devices, and circuits
- Design for manufacturing, yield, and test, System-on-Chip (SoC) and System-in-Package (SiP) design integration
- Emerging technologies, circuits and Applications (MEMS, memory, Internet of Thing, Autonomous cars, Machine Learning, Artificial Intelligence)

Please submit 2-4 pages English paper in IEEE template (<http://www.icicdt.org/Author.html>). For paper submission and submission requirements, please click the website link: <http://www.icicdt.org/Submission.html>

Paper Submission Deadline: April 15th, 2019

Conference Sponsors



Keynote Speakers:



Hanming WU
VP of SMIC, China

He earned PhD from Chinese Academy of Sciences in 1987, and post-doc in UC-Berkeley. More than 20 years industry experience in plasma application in semiconductor processes, including Novellus Systems, Intel Corp and SMIC. Along with 80 published papers, more than 42 granted and pending granted patents in semiconductor processes are to his credit. He has some experience of giving lectures at top universities in USA. Some of research results have been included in the textbook in USA. Since 2001, he has joined and led the pre-study of technology development from 0.18um to 32nm node. As a director of Component Research with SMIC, he is now in charge of 32nm research program. Besides, he is a joined guest professor of Fudan University and Xi'An University of Electronics, Research Professor with Institute of Physics, member of technical board with Institute of Microelectronics, Chinese Academy of Sciences. In 2008, he earned the 2nd class award of National Science and Technology Progress.



Paolo A. Gargini
Former Intel Fellow, Italy

Dr. Gargini was born in Florence, Italy and received a doctorate in Electrical Engineering in 1970 and a doctorate in Physics in 1975 from the Università di Bologna, Italy, both with full honor and marks.

He has done research at Stanford University and at Fairchild Camera and Instrument (Research and Development) in Palo Alto in the early 70s.

Since joining Intel in 1978 he was responsible for Microprocessor technology including 80286 and the 80386 processors. In 1985 he headed the first submicron process development team at Intel. He was also responsible for all equipment selections from 1994 to 2007.

In 1996, Dr. Gargini was elevated to Director of Technology Strategy, Intel Fellow.

He was responsible for worldwide consortia research for the Technology and Manufacturing Group (TMG) from 1993 to 2012; he was member of Sematech, SRC and SIA Boards. Thorough the years Dr. Gargini successfully transferred the foundations of fundamental technologies into Intel such as: Copper interconnects, 248nm and 193nm lithography, Strained Silicon, High-K/Metal-Gate, FinFET and many new materials.

From 1998 to 2015, Dr. Gargini has been the Chairman of the International Technology Roadmap for Semiconductors (ITRS) sponsored by the WSC. Since 2016 he is the Chairman of the International Roadmap for Devices and Systems (IRDS) sponsored by IEEE.

Dr. Gargini became the first Chairman of the Governing Council of the Nanoelectronics Research Initiative (NRI) funded in June 2005 by SIA.

He is co-chairman of the EUVL Symposium.

Dr. Gargini was inducted in the VLSI Research Hall of Fame in 2009.

Dr. Gargini was elevated to IEEE Fellow in 2009 and to International Fellow of the Japan Society of Applied Physics in 2014.

Dr. Gargini is chairman of ETAB of E3S (UCB); he is also a member of NEREID Advisory Board (ETAB) for the European Roadmap.

He is a member of the leadership committee of the IEEE initiative on Future Networks aimed at 5G and Beyond Roadmap.

More Speakers to be Announced Soon.....

Invited Speakers:

No	姓名 name	单位 Affiliation	职称/职位/简介 Title	研究方向 Field
1	李欣昕 Xinxin Li	中科院上海微系统与信息技术研究所 SIMIT,CAS	国家“杰青”和中科院“百人计划”	MEMS
2	黄晓东 Xiaodong Huang	东南大学 Southeast University	教授	MEMS 传感器与检测电路
3	李志宏 Zhihong Li	北京大学 Peking University	MEMS 研究所所长	MEMS
4	任天令 Tianling Ren	清华大学 Tsinghua University	微纳器件与系统研究室主任	MEMS
5	宋青林 Qinglin Song	歌尔股份有限公司 Goertek	总经理	传感器
6	庞慰 Wei Pang	诺思微系统有限公司/天津大学 ROFS MICROSYSTEM/TianjinUniversity	教授	微纳机电系统、柔性压电器件
7	杨宏愿 Hongyuan Yang	苏州敏芯微电子技术股份有限公司 MEMSensing	副总	MEMS
8	金玉丰 Yufeng Jin	北京大学 Peking University	微米纳米加工技术国家重点实验室主任	3D、集成微系统、微系统封装技术
9	沈波 Bo Shen	北京大学 Peking University	长江学者、国家杰出青年基金获得者，现任北京大学物理学院副院长、宽禁带半导体研究中心副主任	GaN
10	朱文辉 Wenhui Zhu	中南大学 Central South University	中组部“千人计划”专家，中南大学教授、博士生导师，973 项目首席科学家，国家科技重大专项 02 专项总体论证专家委员会专家，封测产业创新战略联盟咨询委专家	微电子封装
11	丁孙安 Sunan Ding	中科院苏州纳米所 SINANO,CAS	中科院苏州纳米所研究员、博士生导师，纳米真空互联实验站副总指挥。	半导体薄膜材料与器件物理，材料表征与测试，表面与界面分析，真空技术与应用。
12	王旭光 Xuguang Wang	中科院苏州纳米所 SINANO,CAS	中科院“百人计划”	AI
13	曹晓东 Xiaodong Cao	中科院半导体所 IOS,CAS	主任	高性能数模混合集成电路
14	耿莉 Li Geng	西安交通大学 Xi'an Jiaotong University	教授，微电子学院院长	

15	彭长四 Changsi Peng	苏州大学 Soochow University	特聘教授	
16	Jianfu Zhang	Liverpool John Moores University	Professor	
17	韩素婷 Suting Han	深圳大学 Shenzhen University	广东省杰出青年基金获得者，2010 年起已在 Nature Communications (1 篇) ， Materials Today (1 篇) ， Advanced Materials (9 篇) ， ACS Nano (1 篇) ， Materials Horizons (1 篇) ， Advanced Science (2 篇) ， Small (4 篇) 等国际顶级期刊发表了柔性存储器领域相关高水平论文 60 余篇	非易失型存储器
18	许望颖 Wangying Xu	深圳大学 Shenzhen University	深圳市海外高层次人才引进计划获得者，在 ACS Appl. Mater. Interfaces , J. Mater. Chem. C , Appl. Phys. Lett. , Adv. Energy Mater. , Adv. Funct. Mater.等国际知名期刊发表研究论文近 20 篇	新型显示氧化物薄膜晶体管
19	刘红侠 Hongxia Liu	西安电子科技大学 Xidian University	科技部国际科技重大合作计划，863 计划，国家自然科学基金，陕西重大创新计划评价专家，主持承担国家级和省部级科研项目 50 项，包括 973 项目, 863 项目，国家自然科学基金重点等，获省部级奖励多项，包括国防科技进步一等奖二等奖，信息产业部科技进步奖。	纳米器件物理与可靠性研究
20	Tracy LIU	Nano and Advanced Materials Institute Limited (NAMI , Hong Kong)	Director of Research and Development (Electronics) , recognized with the 1st Prize of "National Institution of Higher Education Scientific Research Award – Natural Science Award" in 2010 and the 2nd Prize of "China's State Natural Science Award" in 2013 , as the Principal Investigator of the Die Attach Adhesive technology has enabled NAMI to be recognized with the Technological Achievement Award in the "2014 Hong Kong Awards for Industries".	synthesis and characterization of nanomaterials as well as their applications in lithium ion battery, solid state lighting and electronic devices
.....More Speakers to be Announced Soon.....				

The 17th IEEE ICICDT 2019

Executive Committee Members

Advisory Committee:	Ming Liu (IMECAS) & Hui Yang (Sinano) & Yin Shi (IOS) & John Peng(SMIC)
2019 Conference Chair	Yilong Hao (PKU)
2019 Conference Co-chair:	Yao-Hui Zhang (Sinano) & Cezhou Zhao (XJTLU) & Mingxiang Wang (Soochow Univ.)
General Chair:	Stefano D'Amico (Univ. of Salento) & Andrea Scarpa (NXP Semiconductors)
Executive Chair:	Bich-Yen Nguyen (Soitec) & Thuy Dao (NXP)
Keynote Chair:	Mariam Sadaka (Soitec) & Yao-Hui Zhang (Sinano)
Technical Conference Chair	Mingxiang Wang (Soochow Univ) & Xiao Gong (NUS) & Cuiqin Xu (Huali) & Yan Wang (TSU)
Local Arrangement Chair:	Helun Song(Sinano) & Ying Li (Soochow Univ.) & Wen Liu (XJTLU) & Shouxiang Li (SICIA)
Tutorial Chair:	Oliver Weber (CEA-Leti)
Exhibition Chair:	Xuefeng Shao (ON Semiconductor) & ZG Tay (ON Semiconductor)
Publicity & Award Chair:	Kin P. Cheung (NIST) & Maojun Wang (PKU)
Publication Chair:	Chun Zhao (XJTLU) & Desheng Jiang (ISCAS) & Yi Zhao(ZJU)
Finance Chair:	Helun Song (Sinano) & Dina Triyoso (TEL) & Wen Liu (XJTLU)
Secretary:	Zhanqiang Ru (Sinano)

For information about paper submission, please contact:
会议论文投稿相关事宜, 可咨询:

1	<p>Chun Zhao 赵春 Xi'an Jiaotong-liverpool University 111 Ren'ai Road Suzhou China E-Mail: chun.zhao@xjtlu.edu.cn</p>
---	--

Secretariat and For information about registration, etc. please contact:
会议注册及其他相关事宜, 可咨询:

1	<p>Wen Liu 刘雯 (Responsible for participant outside China, 负责海外参会人员) Xi'an Jiaotong-liverpool University 111 Ren'ai Road Suzhou China E-Mail: wen.liu@xjtlu.edu.cn TEL:+86-13913118798(From 8 a.m. to 8 p.m. Beijing Time)</p>
2	<p>Zhanqiang Ru 茹占强 (Responsible for Chinese participant, 负责国内参会人员) Suzhou Institute of Nano-tech and Nano-bionics, CAS 398 Ruoshui Road Suzhou China E-Mail: zqru2008@sinano.ac.cn TEL:+86-18915566763(From 8 a.m. to 8 p.m. Beijing Time)</p>